

## Unmatched Cleaning Performance

Entegris' Chuck Cleaning Wafers (CCW) boast a revolutionary cleaning mechanism that meticulously removes contaminants from the chuck surface. This results in improved yield, reduced test errors, and enhanced overall efficiency.

## Compatibility and Flexibility

The Chuck Cleaning Wafers (CCW) are compatible with a wide range of equipment, making them a versatile choice for semiconductor manufacturers worldwide. CCWs are available for:

**PVD:** CCW solves the backside pressure fault problem caused by particles on the chuck. It also contributes to improvement of thin film uniformity. Fixes chucking errors in less than 5 minutes vs. 12 hour wet clean. CCW can be used >100 times with >75% success reducing Helium leak.

**Etch:** CCW solves Helium leak problem caused by particles on the chuck (customers have >75% success reducing Helium leak with CCW). Fixes chucking errors in less than 5 minutes vs. 8 hour wet clean. CCW can be used >100 times.

**Lithography:** CCW solves the problem of hot spot, which causes defocus defect. Prevents critical focus errors on high-throughput, extremely expensive tools. CCW can be used >100 times with >75% success fixing hot spots. ITS has developed new polymer chemistry that is better at picking up polymer without sticking to advanced lithography chucks. The new PM-PLUS part is very flat and can pick up very small particles.

Place CCW with polymer side down when debris is present on chuck.

